



THE DATASHEET OF SF2026B



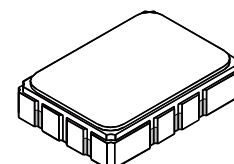
- **Low Insertion Loss**
- **5.0 X 7.0 mm Surface-Mount Case**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 1**
- **AEC-Q200 Qualified**

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Max. DC voltage between any 2 terminals	0	VDC
Storage Temperature Range	-60 to +95	°C
Suitable for lead-free soldering - Max Soldering Temperature	260°C for 30 s	

SF2026B

**114.815 MHz
SAW Filter**



SMP-03

Electrical Characteristics

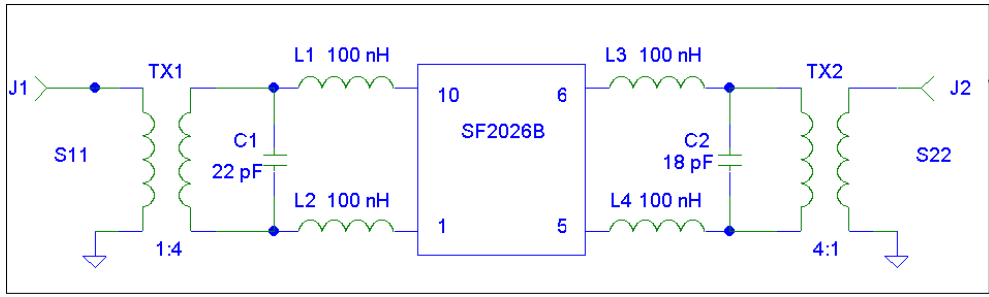
Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency of IF SAW Filter (RF LO ± 50 ppm correction to 1st IF)	f_c		114.815			MHz
Insertion Loss	IL			12.5	15	dB
Amplitude Ripple (p-p) between 111.7594.....113.4107 MHz (BW=1.64 MHz ± 50 ppm)					1.3	dB
Amplitude Ripple (p-p) between 113.5993.....115.2508 MHz (BW=1.64 MHz ± 50 ppm)					1.3	
Amplitude Ripple (p-p) between 115.3492.....117.8709 MHz (BW=1.64 MHz ± 50 ppm)					1.3	
Pass Bandwidth of -1.5 dB				6.30		MHz
Pass Bandwidth of -3 dB				7.24		
Low side attenuation 80 MHz...102.815 MHz ($F_c - 12$ MHz)			38	40		dB
Low side attenuation 102.815 MHz...107.690 MHz ($F_c - 7.125$ MHz)			36	38		
Low side attenuation 107.690 MHz...109.690 MHz ($F_c - 5.125$ MHz)			28	30		
High side attenuation 121.260 ($F_c + 6.445$ MHz)...123.860 MHz ($F_c + 9.045$ MHz)			25	27		
High side attenuation 123.860 MHz...126.815 MHz ($F_c + 12.00$ MHz)			36	38		
High side attenuation 126.815 MHz...150.815 MHz ($F_c + 36.00$ MHz)			38	40		
Group Delay Ripple (p-p) between 111.7594.....113.4107 MHz (BW=1.64 MHz ± 50 ppm)					80	ns
Group Delay Ripple (p-p) between 113.5993.....115.2508 MHz (BW=1.64 MHz ± 50 ppm)					80	ns
Group Delay Ripple (p-p) between 115.3492.....117.8709 MHz (BW=2.510 MHz ± 50 ppm)					100	ns
Operating Temperature Range	T_A		-40		+85	°C
Case Style			SMP-03 7 x 5 mm Nominal Footprint			
Lid Symbolization (YY=year, WW=week, S=shift, ## = Sequence Code)			SF2026B, <u>YYWWS##</u>			

 **CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

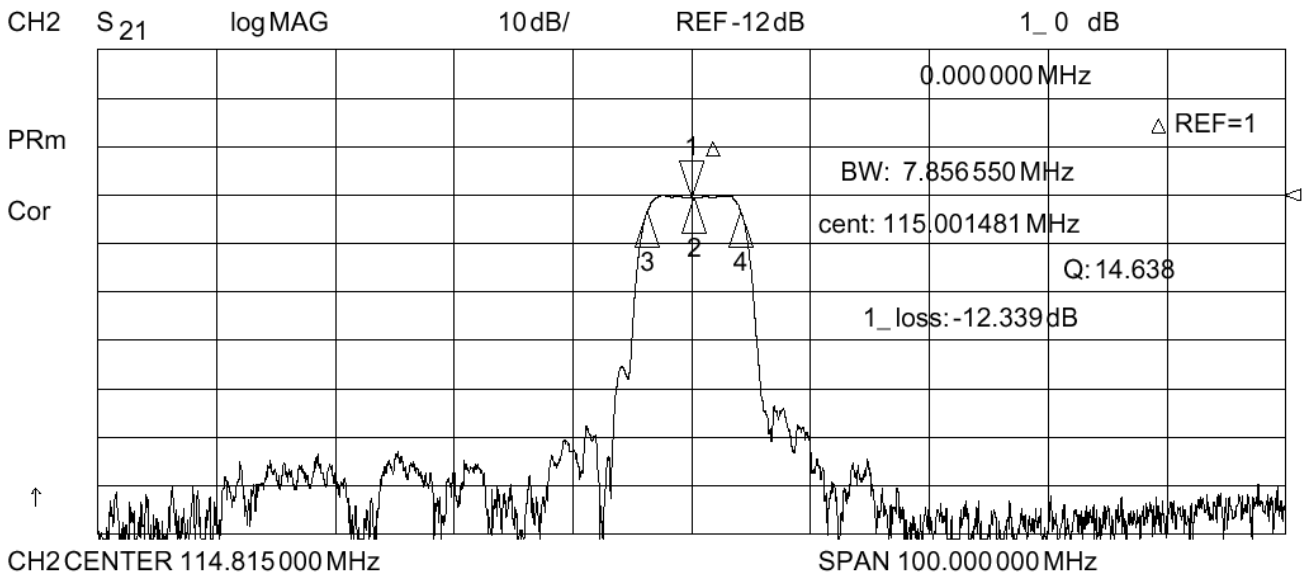
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

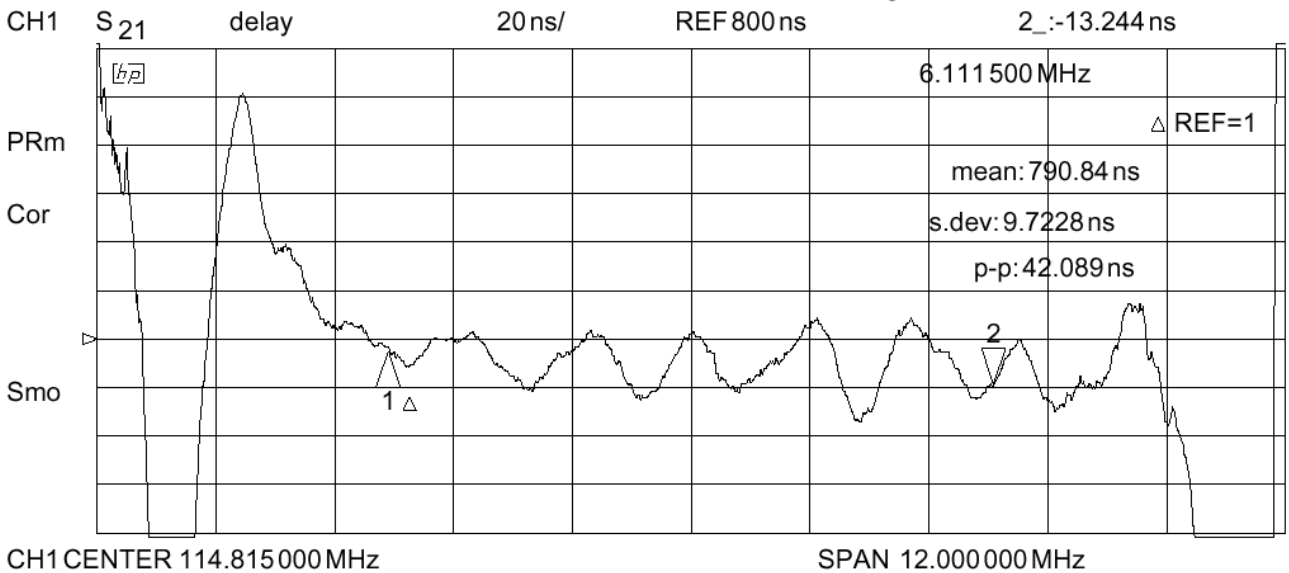
J = 50 Ohms



J = 50 Ohms



28 Aug 2003 09:05:39



28 Aug 2003 09:06:31

CH1 S₁₁ 1 U FS

1_ 40.76

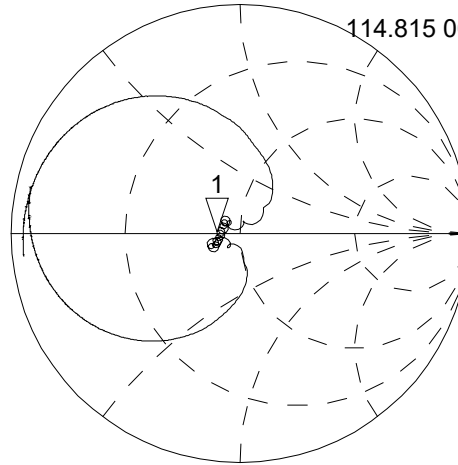
Ω 0.5801

Ω 804.09 pH

114.815 000 MHz

PRm

Cor



↑

CH2 S₂₂ 1 U FS

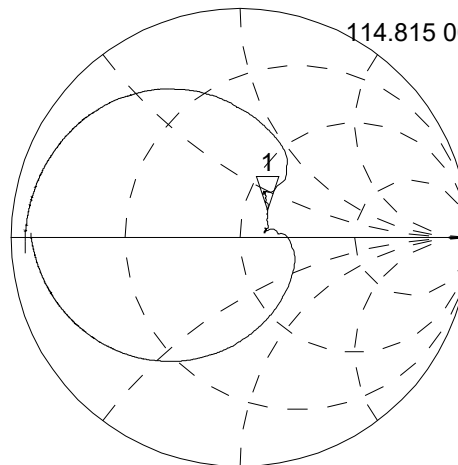
1_ 61.52

Ω 15.119

Ω 20.958 nH

PRm

Cor



↑

CENTER 114.815 000 MHz

SPAN 100.000 000 MHz

SF2026B Recommended Matching

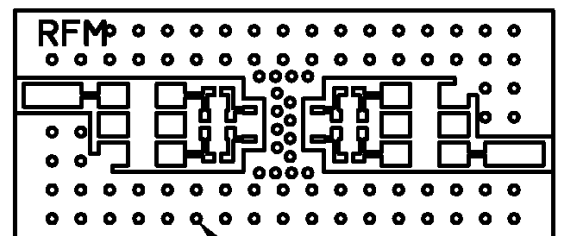
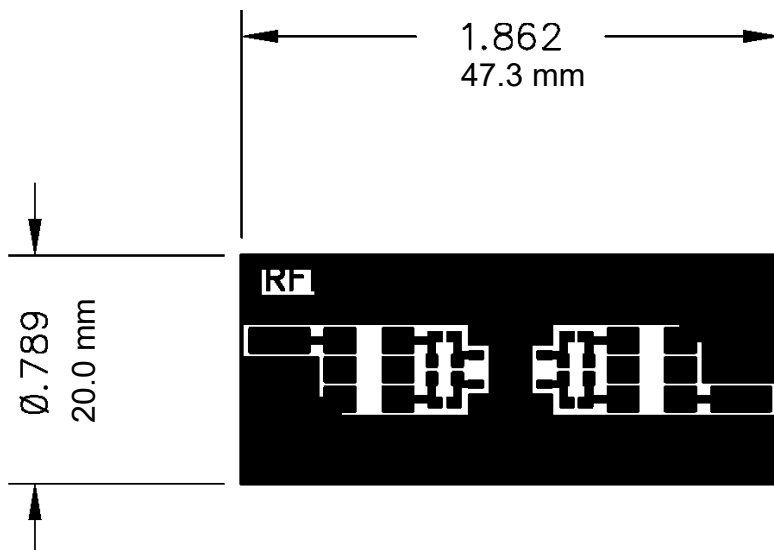
Component for 200 ohm load on Input and Output upon Differential SAW

Inductor

Part Number	0603CSR10XJBW
Value	100nH
Size	0603
Tolerance	5%
Recommended Manufacturer	Coilcraft 0603CS-series

Capacitor

Part Number	0603CG220J9B20	0603CG180J9B20
Value	22 pF	18 pF
Size	0603	0603
Tolerance	±5%	±5%
Recommended Manufacturer	Philips	Philips

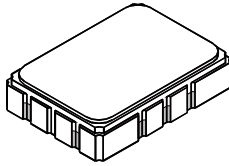


ALL HOLES PLATED THRU - Ø1/32 DRILL

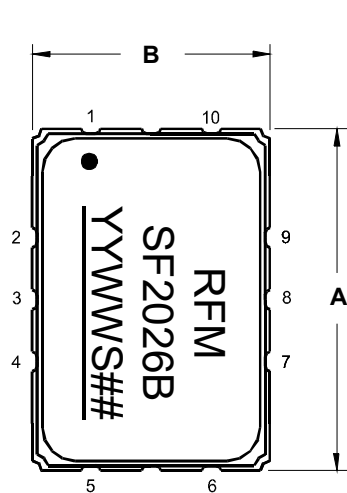
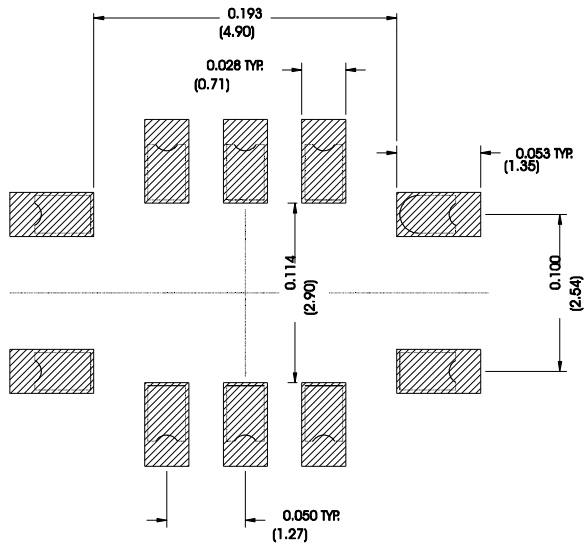
SMP-03 Case

10-Terminal Ceramic Surface-Mount Case

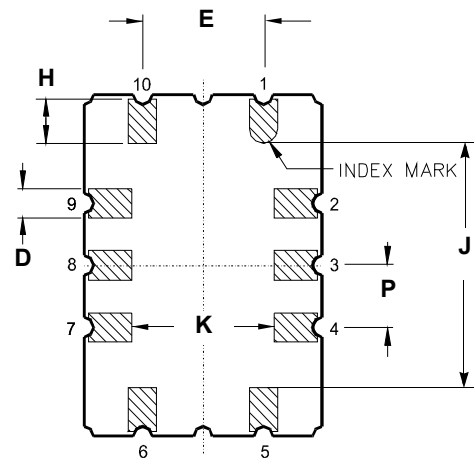
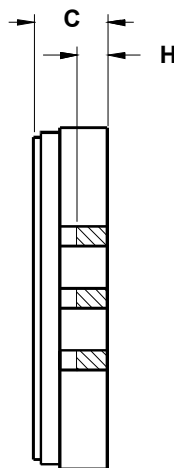
7 x 5 mm Nominal Footprint



Recommended PCB Footprint



TOP VIEW



BOTTOM VIEW

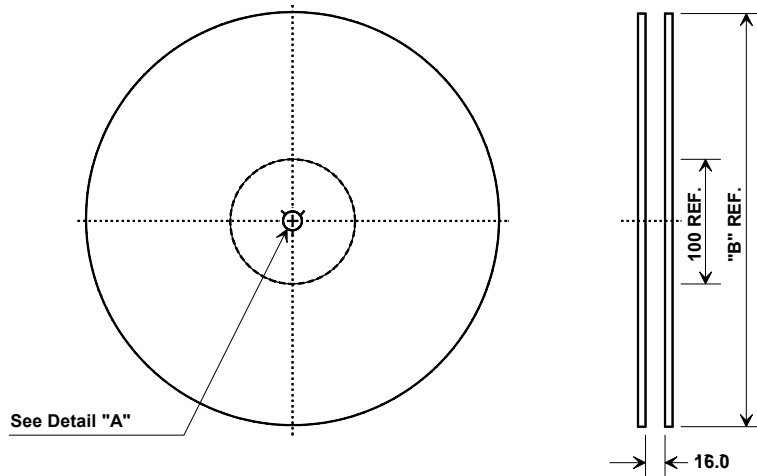
Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	6.80	7.00	7.20	0.268	0.276	0.283
B	4.80	5.00	5.20	0.189	0.197	0.205
C		1.65	2.00		0.065	0.079
D	.47	0.60	.73	0.019	0.024	0.029
E	2.41	2.54	2.67	0.095	0.100	0.105
H	0.87	1.0	1.13	0.034	0.039	0.044
J	4.87	5.00	5.13	0.192	0.197	0.202
K	2.87	3.00	3.13	0.113	0.118	0.123
P	1.14	1.27	1.40	0.045	0.050	0.055

Materials	
Solder Pad Termination	Au plating 30 - 60 ulnches (76.2-152 uM) over 80-200 ulnches (203-508 uM) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 ulnches Thick
Body	Al ₂ O ₃ Ceramic

Electrical Connections		
	Connection	Terminals
Port 1	Input or Return	10
	Return or Input	1
Port 2	Output or Return	5
	Return or Output	6
	Ground	All others
	Single Ended Operation	Return is ground
	Differential Operation	Return is hot

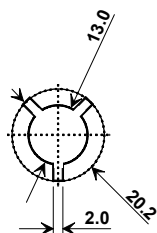
Tape and Reel Specifications

Tape and Reel Standard per ANSI/EIA-481



"B" Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	2000

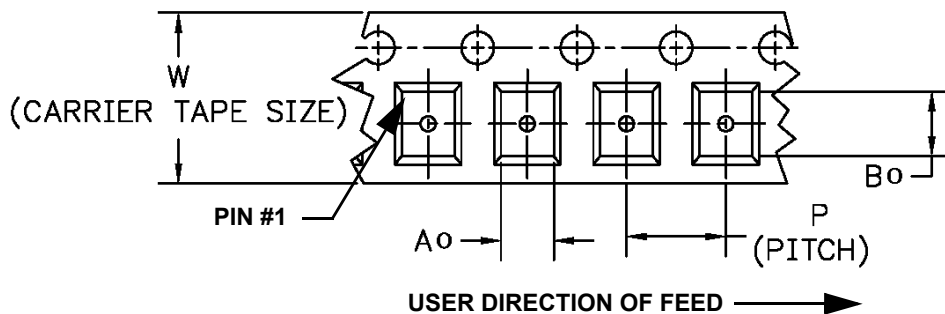
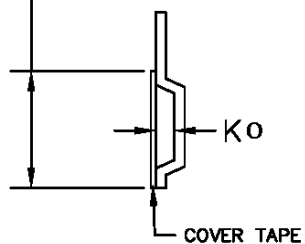
See Detail "A"



COMPONENT ORIENTATION and DIMENSIONS

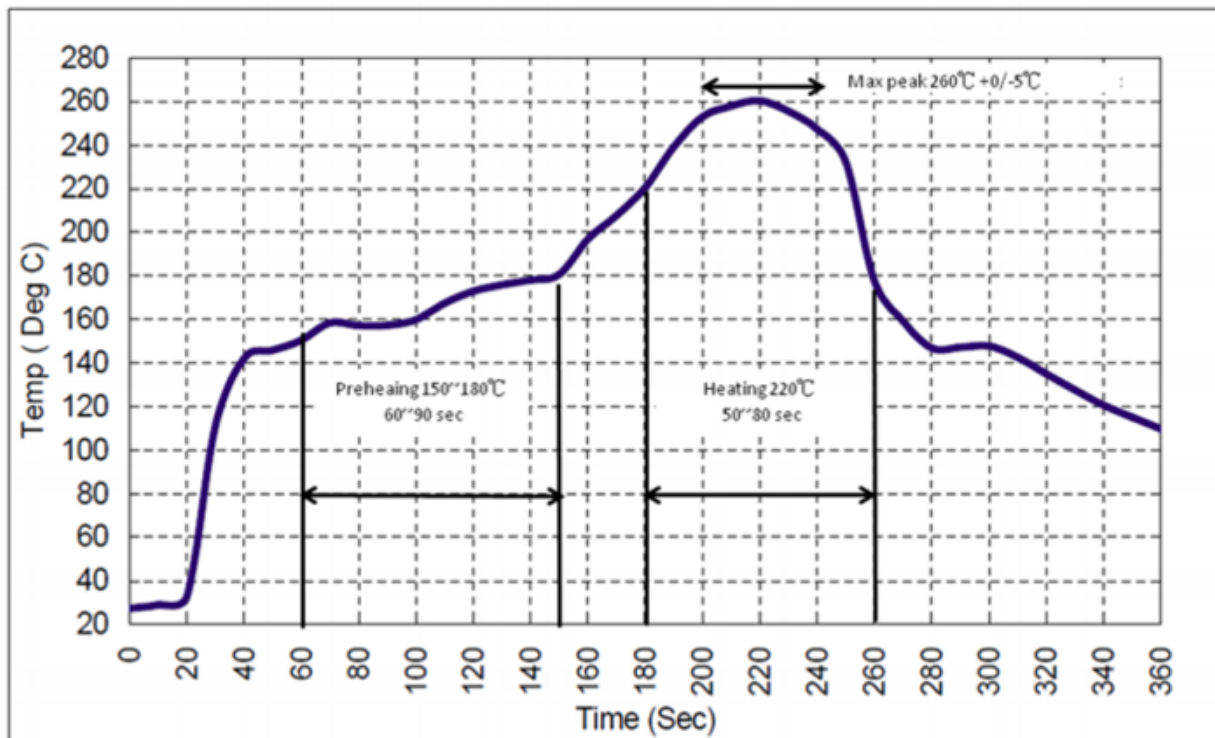
Carrier Tape Dimensions	
Ao	5.5 mm
Bo	7.5 mm
Ko	2.0 mm
Pitch	8.0 mm
W	16.0 mm

COVER TAPE SIZE



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C+0/-5°C peak (10 seconds).
4. Time: 5 times maximum.



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